

Monolithically Integrated Photonic Solutions for All Optical Networks

Presentation for:

The DARPA Workshop on Data in the Optical Domain

March 18, 2003

BinOptics Integrated Photonics

- Technology Platform
 - Monolithic Integration of Multiple Devices on InP
 - High Quality Etched Facets
 - Avoids Coating, Cleaving and Bar Handling
 - Freedom from Cleavage Planes
 - Novel Structures
 - Simplified Wafer-Level Testing

- Photonic Toolbox
 - Ring and FP Lasers
 - Multiple wavelengths
 - Arrays
 - Electroabsorption modulators (EAMs)
 - Photodetectors (PDs)
 - Semiconductor optical amplifiers (SOAs)
 - Beam Couplers/Splitters
 - Waveguides

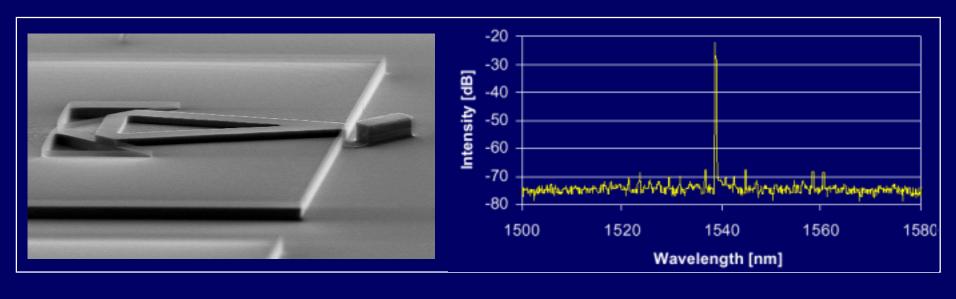
Semiconductor Ring Laser

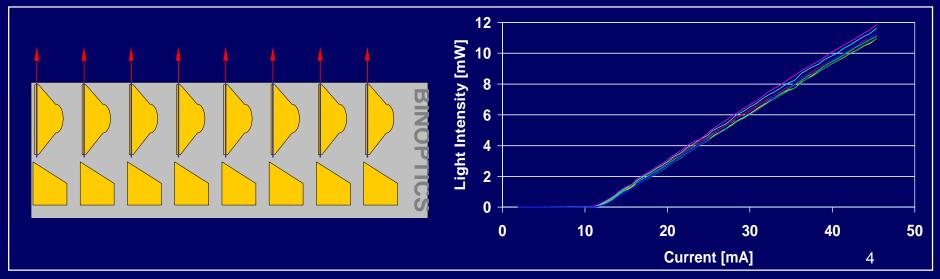
Bidirectional Unidirectional

External Mirror

 Semiconductor ring lasers possess rich dynamic characteristics compared to conventional semiconductor lasers

Examples of Integrated Devices



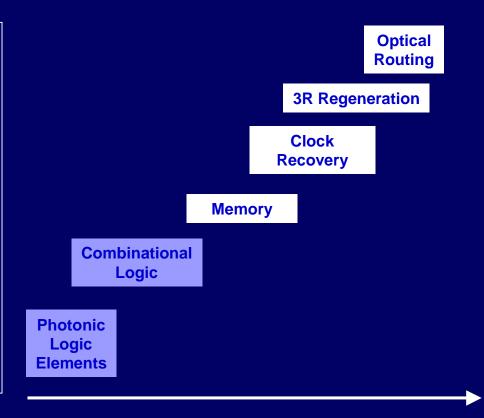


Dynamic Routing and Packet Switching Network

BinOptics Roadmap

Key Required Elements

- photonic switch fabric
- photonic logic
- multi wavelength 2R and 3R optical regenerators
- wavelength converters
- optical isolators
- optical monitoring
- optical delay lines
- optical buffers



BinOptics Technology Platform

 On-Chip Integration of Active and Passive Photonic Elements

- Unmatched Design Flexibility
- Rapid Development and Demonstration of All Optical Networking Functionalities

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